SN54LVTH16952, SN74LVTH16952 3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS697G - JULY 1997 - REVISED APRIL 2000

 Members of the Texas Instruments Widebus™ Family State-of-the-Art Advanced BiCMOS 	SN74LVTH16952	2 WD PACKAGE DGG OR DL PACK P VIEW)	
Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation	10EAB [1 1CLKAB [2	56] 10EBA 55] 1CLKBA	
 Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC}) 	1 CLKENAB [] 3 GND [] 4 1A1 [] 5	54] 1 CLKEN 53] GND 52] 1B1	ВА
 Support Unregulated Battery Operation Down to 2.7 V 	1A2 [6 V _{CC} [7	51] 1B2 50] V _{CC}	
 Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	1A3 [8 1A4 [9	49] 1B3 48] 1B4	
 I_{off} and Power-Up 3-State Support Hot Insertion 	1A5 [10 GND [11 1A6 [12	E	
 Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown 	1A7 [13 1A7 [14	44 [] 1B7	
 Resistors Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise 	2A1 [15 2A2 [16 2A3 [17	41] 2B2	
 Flow-Through Architecture Optimizes PCB Layout 	2A2 [16 2A3 [17 GND [18 2A4 [19 2A5 [20 2A6 [21	39 🛛 GND	
Latch-Up Performance Exceeds 500 mA Per JESD 17		36 [] 2B6	
• ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V	V _{CC} [22 2A7 [23	E E	
Using Machine Model (C = 200 pF, R = 0)	2A8 24 GND 25	E	
Package Options Include Plastic Shrink	2CLKENAB	P	BA
Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil	2CLKAB	E	
Fine-Pitch Ceramic Flat (WD) Package	2 <mark>0EAB</mark> [28	29 20EBA	

description

The 'LVTH16952 devices are 16-bit registered transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input, provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



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Copyright © 2000, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

description (continued)

These devices are fully specified for hot-insertion applications using Ioff and power-up 3-state. The Ioff circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16952 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74LVTH16952 is characterized for operation from -40°C to 85°C.

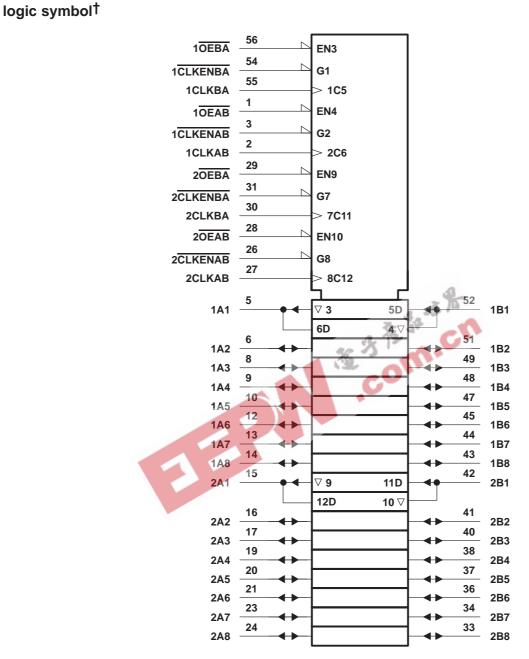
FUNCTION TABLE										
	OUTPUT	1								
CLKENAB	CLKAB	OEAB	Α	В						
Н	Х	L	Х	в ₀ ‡	1					
Х	L	L	Х	в ₀ ‡ в ₀ ‡	L					
L	\uparrow	L	L	L	L					
L	\uparrow	L	Н	н						
Х	Х	Н	Х	Z						

	NOT			-+
Fυ	NCI	ION	TABL	.E I

[†] A-to-B data flow is shown; B-to-A data flow is similar, but uses CLKENBA, CLKBA, and OEBA.

uses CLKENBA, CLKBA, and OEBA. [‡]Level of B before the indicated steady-state input conditions were established

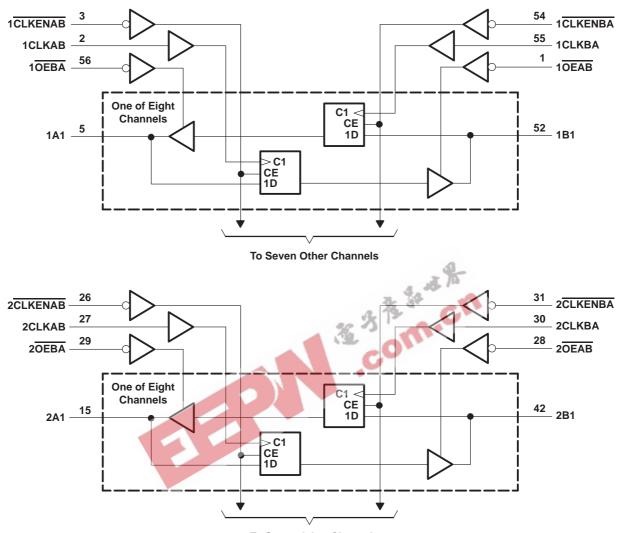




[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To Seven Other Channels



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	
Voltage range applied to any output in the high state, V _O (see Note 1)	
Current into any output in the low state, I _O : SN54LVTH16952	96 mA
SN74LVTH16952	128 mA
Current into any output in the high state, I _O (see Note 2): SN54LVTH16952	48 mA
SN74LVTH16952	64 mA
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I_{OK} (V _O < 0)	
Package thermal impedance, θ_{JA} (see Note 3): DGG package	64°C/W
DL package	
Storage temperature range, T _{stg}	

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$. 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			SN54LVT	H16952	SN74LVT	H16952	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	2.7	3.6	2.7	3.6	V	
VIH	High-level input voltage	2		2		V	
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage			5.5		5.5	V
IOH	High-level output current			-24		-32	mA
IOL	Low-level output current		48		64	mA	
$\Delta t / \Delta v$	Input transition rise or fall rate		10		10	ns/V	
$\Delta t / \Delta V_{CC}$	Power-up ramp rate	200		200		μs/V	
T _A	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TERT	SN54	LVTH1695	52	SN74I	52				
PAR	AMETER	TEST CO	MIN TYP [†] MA			MIN	TYP†	YP† MAX	UNIT		
V_{IK} $V_{CC} = 2.7 V,$			l _l = –18 mA			-1.2			-1.2	V	
		V _{CC} = 2.7 V to 3.6 V,	I _{OH} = -100 μA	V _{CC} -0.2			V _{CC} -0.2				
		V _{CC} = 2.7 V,	I _{OH} =8 mA	2.4			2.4			V	
VOH		Vac. 21/	I _{OH} = -24 mA	2						V	
		$V_{CC} = 3 V$	I _{OH} = -32 mA				2				
			I _{OL} = 100 μA			0.2			0.2		
		$V_{CC} = 2.7 V$	I _{OL} = 24 mA			0.5			0.5		
			I _{OL} = 16 mA			0.4			0.4	V	
VOL			I _{OL} = 32 mA			0.5			0.5	V	
		$V_{CC} = 3 V$	I _{OL} = 48 mA			0.55					
			I _{OL} = 64 mA						0.55		
	Control	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND			±1			±1		
	inputs	V _{CC} = 0 or 3.6 V,	V _I = 5.5 V			10			10		
1		or B $V_{CC} = 3.6 V$	V _I = 5.5 V		- 4a	20	-		20	μA	
	A or B		$V_I = V_{CC}$	a.	A. S.	1			1]	
	pons+		V _I = 0		% - 5		-5		-5	1	
loff	off $V_{CC} = 0$,		$V_{I} \text{ or } V_{O} = 0 \text{ to } 4.5 \text{ V}$	136	01				±100	μΑ	
		N== 01	VI = 0.8 V	75	1		75				
II(hold)	A or B ports	V _{CC} = 3 V	V ₁ = 2 V	-75			-75			μΑ	
. ,		V _{CC} = 3.6 V§,	V _I = 0 to 3.6 V						±500		
IOZPU	-	$\frac{V_{CC}}{OE} = 0 \text{ to } 1.5 \text{ V}, \text{ V}_{O} = 0$	0.5 V to 3 V,			±100			±100	μA	
I _{OZPD}		$\frac{V_{CC}}{OE} = 1.5 \text{ V to } 0, \text{ V}_{O} = 0$	= 0.5 V to 3 V,			±100			±100	μA	
ICC		V _{CC} = 3.6 V,	Outputs high			0.19			0.19		
		$I_{O} = 0,$	Outputs low			5			5	mA	
		$V_{I} = V_{CC} \text{ or GND}$	Outputs disabled			0.19			0.19		
∆ICC¶		$V_{CC} = 3 V$ to 3.6 V, On Other inputs at V_{CC} or				0.2			0.2	mA	
Ci		V _I = 3 V or 0			4			4		pF	
C _{io}		V _O = 3 V or 0			10			10		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. [‡] Unused pins at V_{CC} or GND [§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.



timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			5	SN54LV1	TH16952		5	SN74LV	TH16952		
			= V _{CC} ± 0.		VCC =	2.7 V	= V _{CC} ± 0.		V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			150		150		150		150	MHz
t _w	Pulse duration	CLK high or low	3.3		3.3		3.3		3.3		ns
	Ostern firms	A or B before CLK	2.6		3.3		1.7		2.5		
t _{su}	Setup time	CLKEN before CLK	2.2		2.8		2		2.8		ns
+.	Hold time	A or B after CLK	1		1		0.8		0		ns
th		CLKEN after CLK	1.4		1.5		0.4		0		115

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

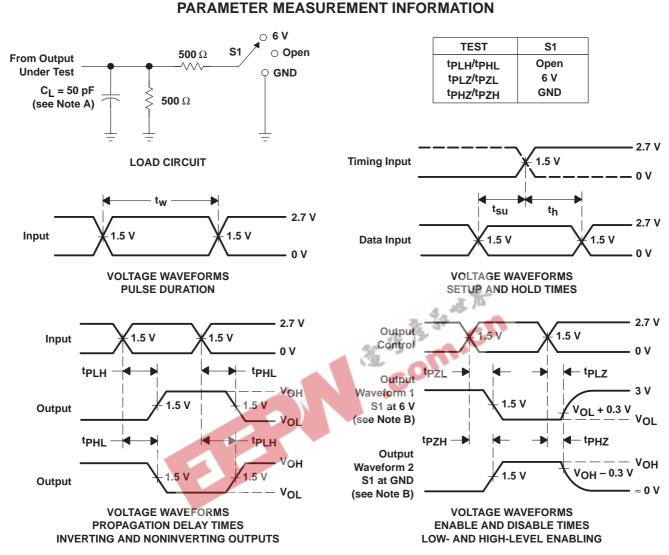
			5	SN54LV1	FH16952		SN74	LVTH1	6952		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	= V _{CC} ± 0.		V _{CC} = 2.7 V	V _{CC} = 3.3 V ± 0.3 V V _{CC}		V _{CC} =	2.7 V	UNIT	
			MIN	MAX	MIN MAX	MIN	TYP [†]	MAX	MIN	MAX	
f _{max}			150	. 2	150	150			150		MHz
^t PLH	CLKBA or	A or B	1.6	5.7	7.4	1.3	2.7	4		4.4	ns
^t PHL	CLKAB	AUB	1.7	6	7	1.3	2.7	4		4.4	115
^t PZH	OEBA or OEAB	A or B	0.9	5	7.3	1	2.3	4		4.9	ns
^t PZL	OEBA OF OEAB	AOID	1.1	5.2	5.9	1	2.4	4		4.9	115
^t PHZ		A or B	1.7	6.7	7.3	2.1	3.9	5.7		6.2	ns
^t PLZ	OEBA or OEAB	AUB	1.1	5.8	6	2.1	3.5	5.1		5.3	115

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



SN54LVTH16952, SN74LVTH16952 3.3-V ABT 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

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NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9684901QXA	ACTIVE	CFP	WD	56	1	TBD	Call TI	Level-NC-NC-NC
74LVTH16952DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
74LVTH16952DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16952DGGR	ACTIVE	TSSOP	DGG	56	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LVTH16952DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16952DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LVTH16952WD	ACTIVE	CFP	WD	56	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

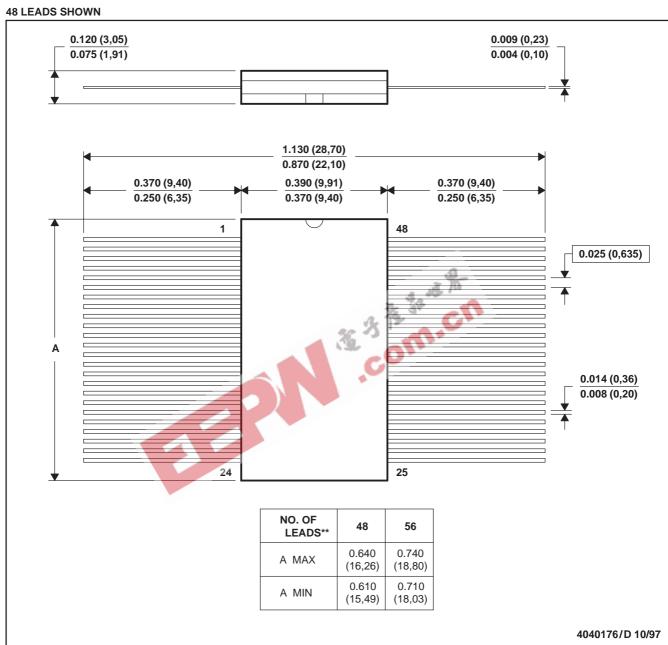
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MECHANICAL DATA

MCFP010B - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).

WD (R-GDFP-F**)

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO -146AA GDFP1-F56 and JEDEC MO -146AB

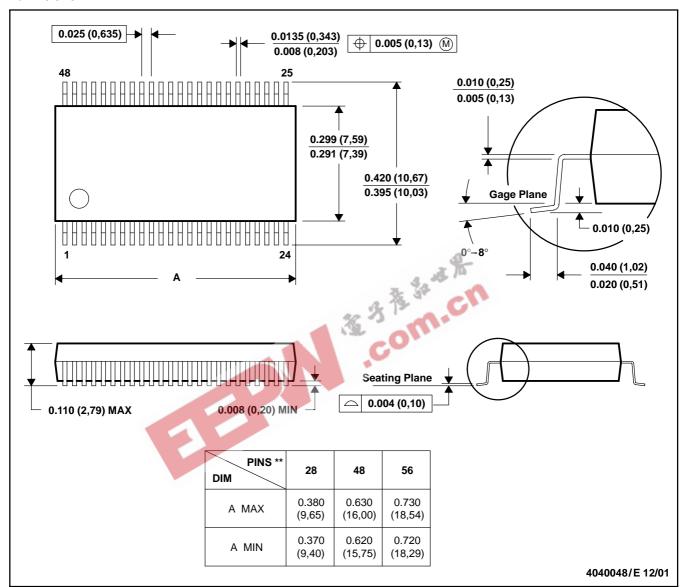


MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

DL (R-PDSO-G**) 48 PINS SHOWN



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NOTES: A. All linear dimensions are in inches (millimeters).

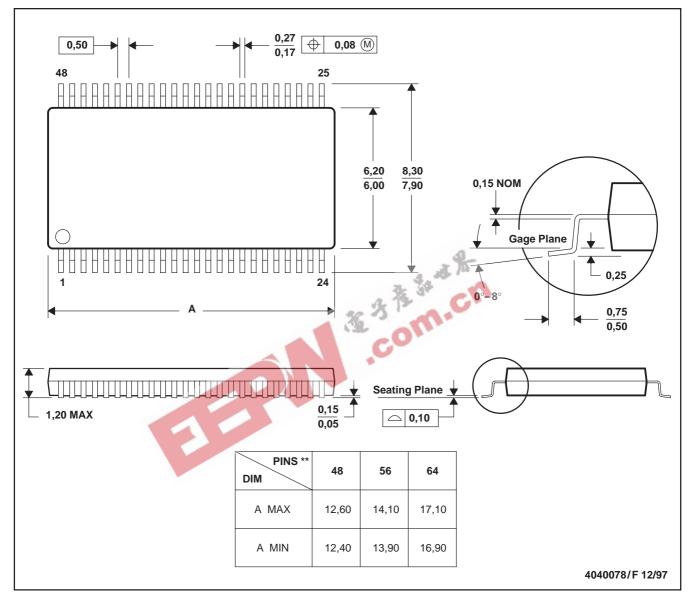
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

PLASTIC SMALL-OUTLINE PACKAGE

DGG (R-PDSO-G**) 48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



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